

## Features

- Glass passivated chip
- Super fast switching for high efficiency
- For surface mounted applications
- Low forward voltage drop and high current capability
- Low reverse leakage current
- Plastic material used carries underwriters laboratory classification 94V-0



DO-214AC (SMA)

## Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	ES2AA	ES2BA	ES2CA	ES2DA	ES2FA	ES2GA	ES2JA	Unit
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	50	100	150	200	300	400	600	V
Maximum RMS Voltage	V <sub>RMS</sub>	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current @ T <sub>L</sub> =110°C	I <sub>F(AV)</sub>	2.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine-wave Superimposed on Rated Load	I <sub>FSM</sub>	50							A
Typical Thermal Resistance <sup>1</sup>	R <sub>θJA</sub>	77							°C/W
	R <sub>θJC</sub>	33							
	R <sub>θJL</sub>	7							
Operating Junction Temperature Range	T <sub>J</sub>	-55 to +150							°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150							°C

## Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	ES2AA	ES2BA	ES2CA	ES2DA	ES2FA	ES2GA	ES2JA	Unit
Maximum Instantaneous Forward Voltage	I <sub>F</sub> =2.0A, DC	V <sub>F</sub>	0.92				1.25		1.7	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	T <sub>L</sub> =25°C	I <sub>R</sub>	5							uA
	T <sub>L</sub> =125°C		350							
Typical Reverse Recovery Time	I <sub>F</sub> =0.5A, I <sub>R</sub> =1.0A, I <sub>RR</sub> =0.25A	t <sub>rr</sub>	35							nS
Typical Junction Capacitance	4.0V 1MHz	C <sub>J</sub>	25							pF

Notes:1. The thermal resistance from junction to ambient,case or lead,mounted on P.C.B with 5×5mm copper pads, 2 OZ, FR4 PCB.

## Typical Characteristics Curves

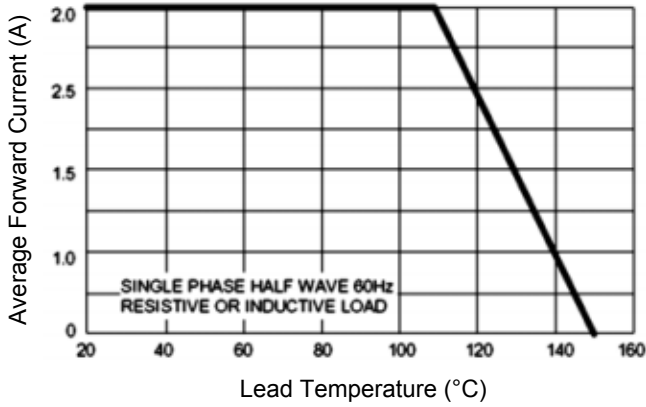


Figure 1. Forward Current Derating Curve

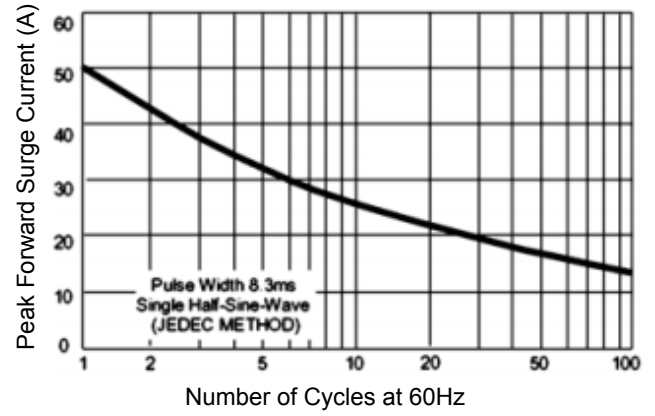


Figure 2. Maximum Non-Repetitive Surge Current

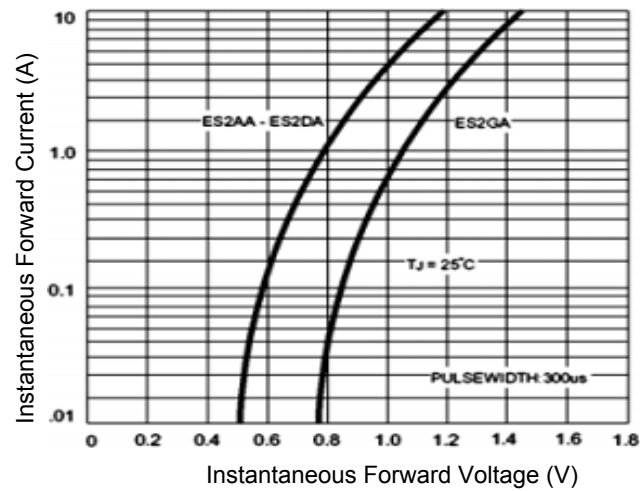


Figure 3. Typical Forward Characteristics

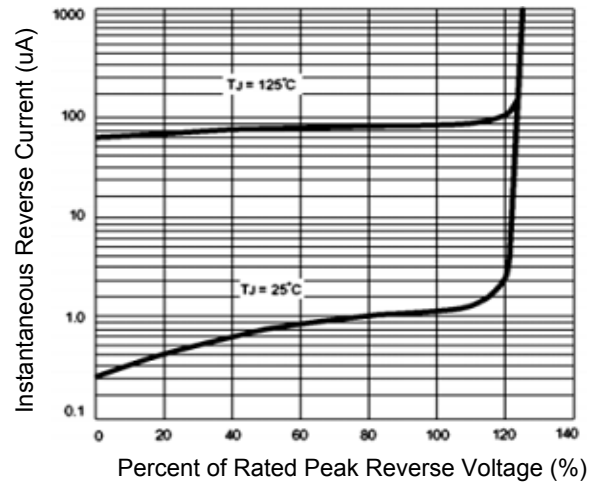


Figure 4. Typical Reverse Characteristics

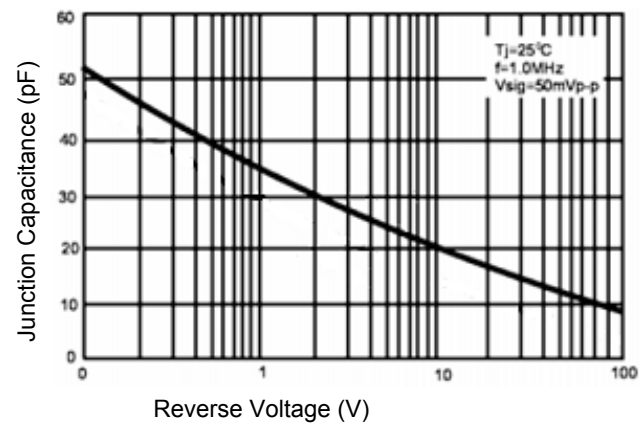
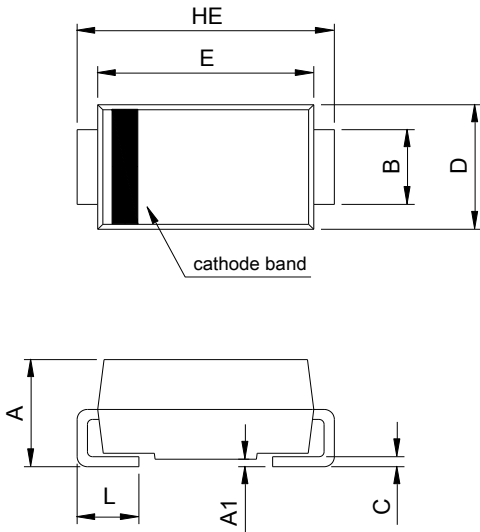


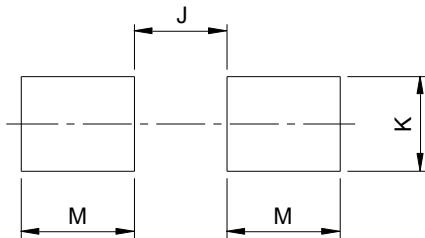
Figure 5. Typical Junction Capacitance

## Package Outline Dimensions DO-214AC (SMA)



SMA (DO-214AC)				
DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.90	2.30	0.075	0.091
A1	0.00	0.20	0.000	0.008
B	1.25	1.65	0.049	0.065
C	0.15	0.31	0.006	0.012
D	2.35	2.90	0.093	0.114
E	3.99	4.60	0.157	0.181
HE	4.80	5.30	0.189	0.209
L	0.76	1.52	0.030	0.060

## Recommended Pad Layout



Recommended Pad Layout (Reference ONLY)				
DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
J	-	2.20	-	0.087
K	1.72	-	0.068	-
M	2.00	-	0.079	-